

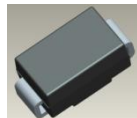
**2.0A HIGH VOLTAGE SCHOTTKY BARRIER RECTIFIER**

**Features**

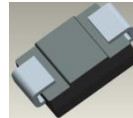
- Schottky Barrier Chip
- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Surge Overload Rating to 50A Peak
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Application
- High Temperature Soldering: +260°C/10 Second at Terminal
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

**Mechanical Data**

- Case: SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208③
- Polarity: Cathode Band or Cathode Notch
- Weight: 0.093 grams (Approximate)



Top View



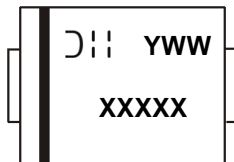
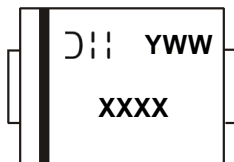
Bottom View

**Ordering Information** (Note 4)

Part Number	Case	Packaging
B2xx-13-F	SMB	3000/Tape & Reel
B2xxx-13-F	SMB	3000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

**Marking Information**



XXXX/XXXXX = Product Type Marking Code, ex: B290 (SMB Package)  
 ⏏ = Manufacturers' Code Marking  
 YWW = Date Code Marking  
 Y = Last Digit of Year (ex: 7 for 2017)  
 WW = Week Code (01 to 53)

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	B270	B280	B290	B2100	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>					
Working Peak Reverse Voltage	V <sub>RWM</sub>	70	80	90	100	V
DC Blocking Voltage	V <sub>R</sub>					
RMS Reverse Voltage	V <sub>R(RMS)</sub>	49	56	63	70	V
Average Rectified Output Current @ T <sub>T</sub> = +125°C	I <sub>O</sub>	2.0				A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	50				A

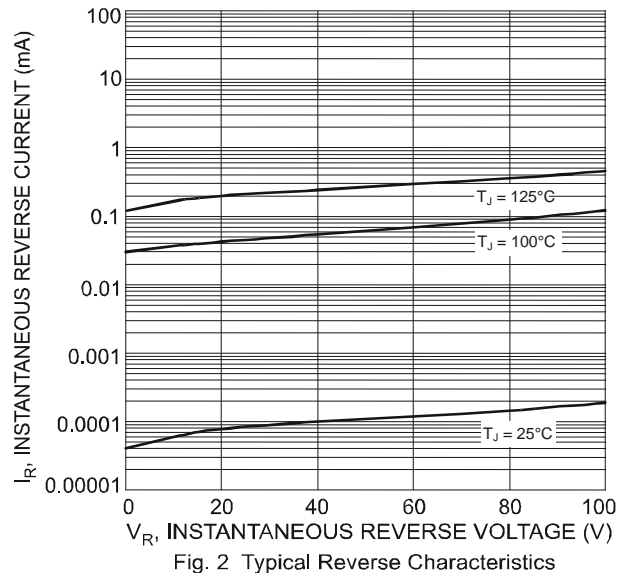
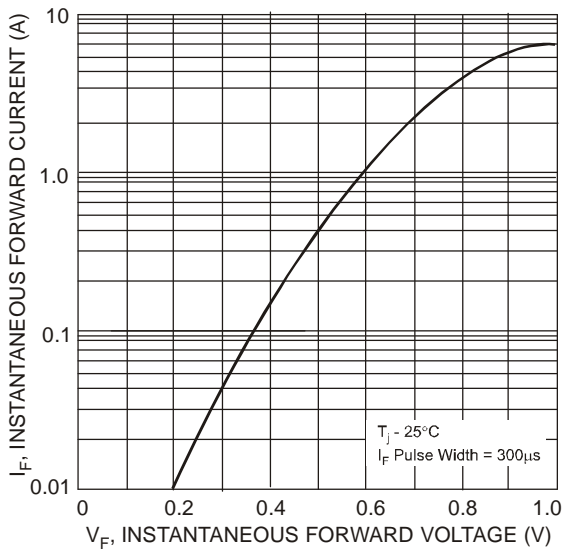
**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Terminal (Note 5)	R <sub>θJT</sub>	15	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V <sub>F</sub>	—	—	0.79 0.69	V	I <sub>F</sub> = 2.0A, T <sub>A</sub> = +25°C I <sub>F</sub> = 2.0A, T <sub>A</sub> = +100°C
Leakage Current (Note 6)	I <sub>R</sub>	—	—	7.0 2.0	μA mA	@ Rated V <sub>R</sub> , T <sub>A</sub> = +25°C @ Rated V <sub>R</sub> , T <sub>A</sub> = +100°C
Total Capacitance	C <sub>T</sub>	—	—	75	pF	V <sub>R</sub> = 4V, f = 1MHz

Notes: 5. Valid provided that terminals are kept at ambient temperature.  
6. Short duration pulse test used to minimize self-heating effect.  
7. DUT mounted on 1\*MRP FR-4 PC board, 2oz.



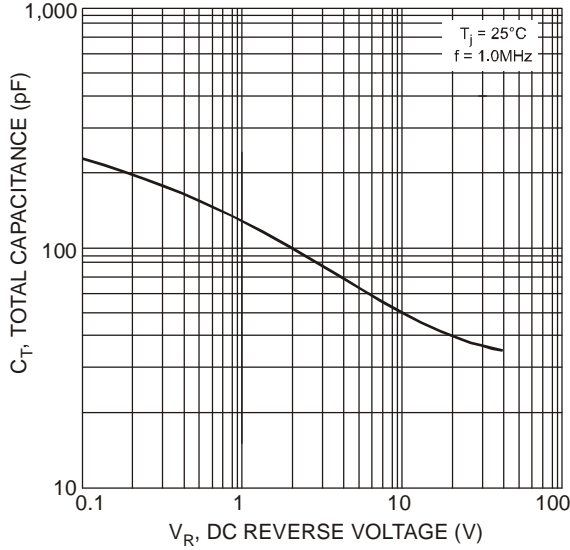


Fig. 3 Total Capacitance vs. Reverse Voltage

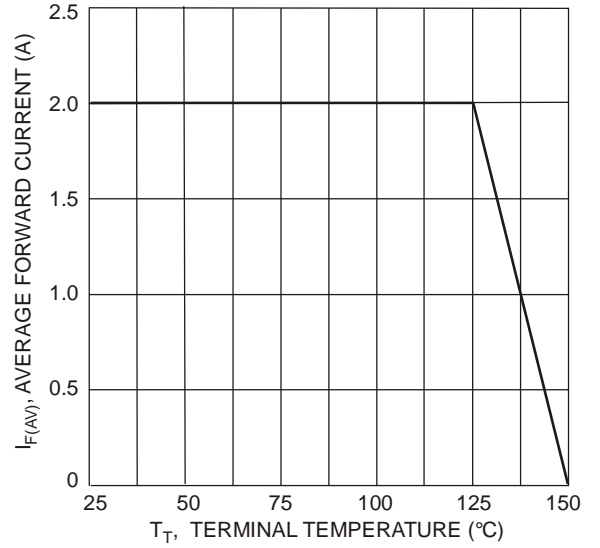


Fig. 4 Forward Current Derating Curve

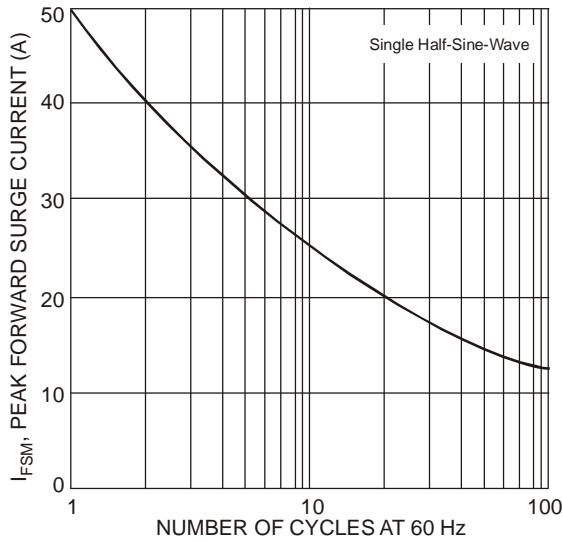


Fig. 5 Max Non-Repetitive Peak Forward Surge Current

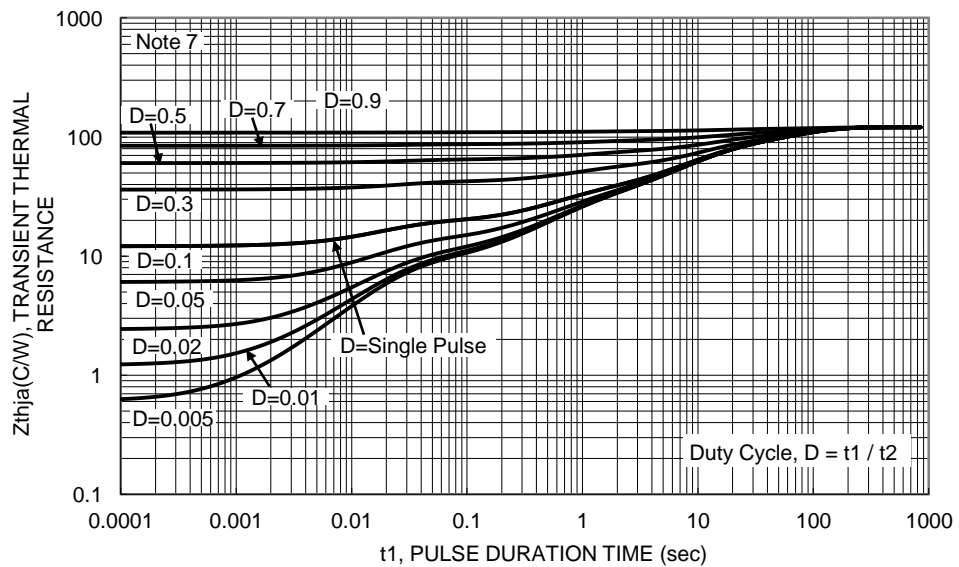


Figure 6. Transient Thermal Resistance

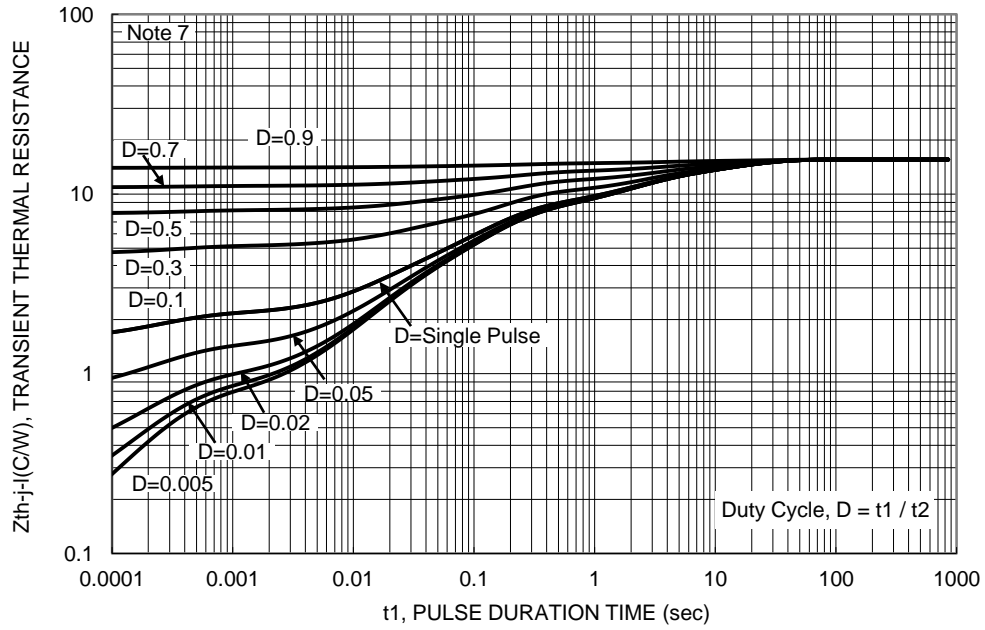
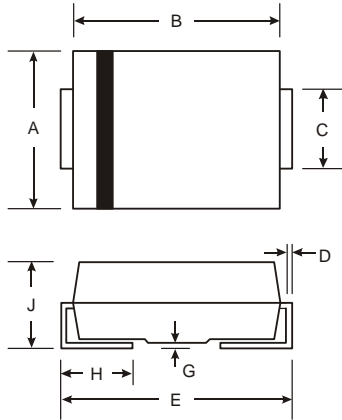


Figure 7. Transient Thermal Resistance

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### SMB

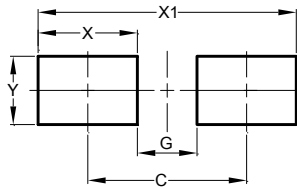


SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.57
C	1.96	2.21
D	0.15	0.31
E	5.00	5.59
G	0.05	0.20
H	0.76	1.52
J	2.00	2.50
All Dimensions in mm		

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### SMB



Dimensions	Value (in mm)
C	4.30
G	1.80
X	2.50
X1	6.80
Y	2.30

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